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Contents Lists and Abstracts from the China Journal "Technology on Adhesion & Sealing"

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Curing Reaction Property and Bonding Strength of Epoxy Resin-Low Molecular Polyamide System

Lan LIWEN, Ji TIEZHENG, Zhou JUNHUI, Yu HONGLAN

Northwest China Institute of Technology

Curing reaction property of bisphenol A epoxy resin-low molecular polyamide system in a wide range of curing temperature was studied with DSC method, and the relation between curing degree and joint form was also studied in this paper.

Study on Synthesis of Bisphenol-S Epoxy Resin with Phase Transfer Catalysis

Gao JUNGANG, Liu YINHAI, Wang FENGLI, Shi LINQI

Department of Chemistry, Hebei University

Bisphenol-S epoxy resin has been synthesized with phase transfer catalysis. This is a convenient, rapid and efficient method for the synthesis of lower or higher molecular weight bisphenol-S epoxy resin. The method involves the reaction of bisphenol-S with epichlorohydrin in aqueous alkali-dioxane or ethyl system, at 75°C–95°C. The polyethylene glycols are used as phase transfer catalysts. The product is obtained in the form of powder. Its intrinsic viscosity is 3~28 ml/g.

The Effect of the Polar Group on Acrylic Pressure Sensitive Adhesives

Liu TONGBOA, Wang FENGGUO, Hu JINGLING, Li JIANQI

Department of Chemistry, Hangzhou University

Several pressure sensitive adhesives (PSA) of acrylic copolymers containing polar groups were prepared.

The effects of the polar nature of functional groups on viscosity of raw adhesive liquid on cohesion, adhesion and tack of PSA were studied.

The concept which evaluates overall performance of PSA was suggested. Based on this concept, a PSA having good performance was found.

Durability of Joint of Structural epoxy Adhesive Toughened by Rubber

Ma MANZHEN, Li XIMIN, Guan SIFENG

Northwest China Institute of Technology

The stress corrosive test was made on Adhesive 84-1, an epoxy adhesive modified by random carboxyl succinonitrile adhesive, under the action of temperature, water and stress with the stress corrosion loading unit the authors made. To determine the durability of Adhesive 84-1 and 84-2, an epoxy adhesive modified with succinonitrile Adhesive-40, the tests were made under the condition of immersing them in the water at 80°C for over a long period. The microscopic structural analysis made by infrared spectrum diagram and electron microscopy have shown that there are effects of toughening mechanism on the adhesive durability.

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Research and Application of Wear-resisting Epoxy Adhesive

Huang ZENGYAN

Changsha Chemical Engineering Institute

The composition, properties and construction technology of wear-resisting epoxy adhesive are mainly studied. The experimental results show that the adhesive has high thermal deformation temperature and shear strength, especially it has good electrical property and wear-resisting property, so it is widely used in maintenance of equipment, especially in wear-resisting coat for slideaway of machine tool and sealing insulated part of electrical equipment.

Polyurethane Emulsion Adhesive

Li SHAOXIONG, Jiang FUMING

Jiangsu Chemical Engineering Institute

The preparation process of polyurethane emulsion and vinyl polyurethane emulsion and their applied results are discussed detailed in this paper.

Reliability of Adhesional Sealing Optoelectronic Semiconductor Devices

Guo ZANMING

No. 44 Institute, the Ministry of Electronics Industry

The effect of degradations due to heat and atmosphere on reliability for adhesional sealing optoelectronic semiconductor devices with window and fiber is studied in this paper. And by means of the TBA, the curing process for several room temperature adhesives is also investigated, so that the correct thermosetting conditions and limit of the reliability for adhesional sealing devices are pointed out.